

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Solder Film Manufacturing Method, Heat Sink Furnished with Solder Film, and Semiconductor-Device-and-Heat-Sink Junction	
Application Number :		
Date :		
First Named Applicant:	Mr. Katsuhiro Itakura	
Confirmation Number:		
Attorney Docket Number:	39.036	
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>		
Submitted By: James Judge Registered Number: 42,701	Elec. Sign. jjUDGE	Sign. Capacity Agent

Documents being submitted:	Files
us-assignment	SM036-usassn.xml us-assignment.xsl us-assignment.dtd assgn.tif
us-request	SM036-usreq.xml us-request.dtd us-request.xsl
us-fee-sheet	SM036-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
application-body	SM036-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomsr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd dclr01.tif dclr02.tif dclr03.tif
Comments	